

ABSTRACT OF THE DISCLOSURE

EPOXY RESIN COMPOSITION AND RESIN-ENCAPSULATED SEMICONDUCTOR
DEVICE

An epoxy resin composition comprising (A) a bifunctional crystalline epoxy compound, (B) an amorphous trisphenolmethane type epoxy compound having three or more of epoxy groups in a molecule, and (C) an epoxy curing agent having phenolic hydroxyl groups. The resin composition has an excellent moldability (low viscosity and can be filled with filler with high density) and high softening point, and is used preferably as an encapsulating material for electronic device.